

1-Ω SPDT ANALOG SWITCH

5-V/3.3-V SINGLE-CHANNEL 2:1 MULTIPLEXER/DEMULTIPLEXER

Check for Samples: [TS5A3160](#)

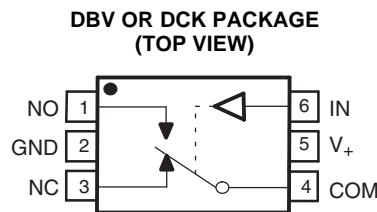
FEATURES

- Isolation in the Powered-Off Mode, $V_+ = 0$
- Specified Make-Before-Break Switching
- Low ON-State Resistance (1 Ω)
- Control Inputs Are 5.5-V Tolerant
- Low Charge Injection
- Excellent ON-State Resistance Matching
- Low Total Harmonic Distortion (THD)
- 1.65-V to 5.5-V Single-Supply Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
 - 2000-V Human-Body Model (A114-B, Class II)

– 1000-V Charged-Device Model (C101)

APPLICATIONS

- Cell Phones
- PDAs
- Portable Instrumentation
- Audio and Video Signal Routing
- Low-Voltage Data Acquisition Systems
- Communication Circuits
- Modems
- Hard Drives
- Computer Peripherals
- Wireless Terminals and Peripherals



DESCRIPTION/ORDERING INFORMATION

The TS5A3160 is a single-pole double-throw (SPDT) analog switch that is designed to operate from 1.65 V to 5.5 V. The device offers a low ON-state resistance and an excellent channel-to-channel ON-state resistance matching. The device has excellent total harmonic distortion (THD) performance and consumes very low power. These features make this device suitable for portable audio applications.

Table 1. ORDERING INFORMATION

| T _A | PACKAGE ⁽¹⁾ (2) | | ORDERABLE PART NUMBER | TOP-SIDE MARKING ⁽³⁾ |
|----------------|----------------------------------|---------------|-----------------------|---------------------------------|
| –40°C to 85°C | SOT (SOT-23) – DBV | Tape and reel | TS5A3160DBVR | JAK_ |
| | SOT (SC-70) – DCK ⁽³⁾ | Tape and reel | TS5A3160DCKR | JK_ |
| | SOT (SC-70) – DCK | Tape and reel | TS5A3160DCKJ | JK_ |

(1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

(3) DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Table 2. Summary of Characteristics⁽¹⁾

| Configuration | 2:1 Multiplexer/ Demultiplexer (1 × SPDT) |
|---|---|
| Number of channels | 1 |
| ON-state resistance (r_{on}) | 1.1 Ω |
| ON-state resistance match (Δr_{on}) | 0.1 Ω |
| ON-state resistance flatness ($r_{on(flat)}$) | 0.15 Ω |
| Turn-on/turn-off time (t_{ON}/t_{OFF}) | 20 ns/15 ns |
| Make-before-break time (t_{MBB}) | 12 ns |
| Charge injection (Q_C) | 36 pC |
| Bandwidth (BW) | 100 MHz |
| OFF isolation (O_{ISO}) | –65 dB at 1 MHz |
| Crosstalk (X_{TALK}) | –66 dB at 1 MHz |
| Total harmonic distortion (THD) | 0.01% |
| Leakage current ($I_{COM(OFF)}/I_{NC(OFF)}$) | ± 20 nA |
| Power-supply current (I_+) | 0.1 μ A |
| Package options | 6-pin DBV or DCK |

(1) $V_+ = 5$ V and $T_A = 25^\circ\text{C}$ **FUNCTION TABLE**

| IN | NC TO COM, COM TO NC | NO TO COM, COM TO NO |
|----|-------------------------|-------------------------|
| L | ON | OFF |
| H | OFF | ON |

ABSOLUTE MINIMUM AND MAXIMUM RATINGS^{(1) (2)}

over operating free-air temperature range (unless otherwise noted)

| | | | MIN | MAX | UNIT |
|-----------------------------------|--|---|------|-------------|------|
| V_+ | Supply voltage range ⁽³⁾ | | –0.5 | 6.5 | V |
| V_{NC} V_{NO} V_{COM} | Analog voltage range ^{(3) (4) (5)} | | –0.5 | $V_+ + 0.5$ | V |
| I_K | Analog port diode current | $V_{NC}, V_{NO}, V_{COM} < 0$ | –50 | | mA |
| I_{NC} I_{NO} I_{COM} | On-state switch current | $V_{NC}, V_{NO}, V_{COM} = 0 \text{ to } V_+$ | –200 | 200 | mA |
| | On-state peak switch current ⁽⁶⁾ | | –400 | 400 | |
| V_I | Digital input voltage range ^{(3) (4)} | | –0.5 | 6.5 | V |
| I_{IK} | Digital input clamp current | $V_I < 0$ | –50 | | mA |
| I_+ | Continuous current through V_+ | | | 100 | mA |
| I_{GND} | Continuous current through GND | | –100 | | mA |
| θ_{JA} | Package thermal impedance ⁽⁷⁾ | DBV package | | 165 | °C/W |
| | | DCK package | | 259 | |
| T_{stg} | Storage temperature range | | –65 | 150 | °C |

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum
- (3) All voltages are with respect to ground, unless otherwise specified.
- (4) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (5) This value is limited to 5.5 V maximum.
- (6) Pulse at 1-ms duration < 10% duty cycle
- (7) The package thermal impedance is calculated in accordance with JESD 51-7.

ELECTRICAL CHARACTERISTICS FOR 5-V SUPPLY⁽¹⁾
 $V_+ = 4.5 \text{ V to } 5.5 \text{ V}$, $T_A = -40^\circ\text{C to } 85^\circ\text{C}$ (unless otherwise noted)

| PARAMETER | SYMBOL | TEST CONDITIONS | T_A | V_+ | MIN | TYP | MAX | UNIT |
|---|----------------------------------|---|----------------------|-------|-------------|-------------|--------------|---------------|
| Analog Switch | | | | | | | | |
| Analog signal range | V_{COM}, V_{NC}, V_{NO} | | | | 0 | | V_+ | V |
| Peak ON resistance | r_{peak} | $0 \leq (V_{NO} \text{ or } V_{NC}) \leq V_+$, $I_{COM} = -100 \text{ mA}$, Switch ON, See Figure 13 | 25°C Full | 4.5 V | | 0.8 | 1.1 1.5 | Ω |
| ON-state resistance | r_{on} | $V_{NO} \text{ or } V_{NC} = 2.5 \text{ V}$, $I_{COM} = -100 \text{ mA}$, Switch ON, See Figure 13 | 25°C Full | 4.5 V | | 0.7 | 0.9 1.1 | Ω |
| ON-state resistance match between channels | Δr_{on} | $V_{NO} \text{ or } V_{NC} = 2.5 \text{ V}$, $I_{COM} = -100 \text{ mA}$, Switch ON, See Figure 13 | 25°C Full | 4.5 V | | 0.05 | 0.1 0.1 | Ω |
| ON-state resistance flatness | $r_{on(flat)}$ | $0 \leq (V_{NO} \text{ or } V_{NC}) \leq V_+$, $I_{COM} = -100 \text{ mA}$, $V_{NO} \text{ or } V_{NC} = 1 \text{ V}, 1.5 \text{ V}, 2.5 \text{ V}$, $I_{COM} = -100 \text{ mA}$, Switch ON, See Figure 13 | 25°C 25°C Full | 4.5 V | | 0.15 0.1 | 0.25 0.25 | Ω |
| NC, NO OFF leakage current | $I_{NC(OFF)}, I_{NO(OFF)}$ | $V_{NC} \text{ or } V_{NO} = 1 \text{ V}$, $V_{COM} = 4.5 \text{ V}$, or $V_{NO} = 4.5 \text{ V}, V_{COM} = 1 \text{ V}$, Switch OFF, See Figure 14 | 25°C Full | 5.5 V | -20 -100 | 2 | 20 100 | nA |
| | $I_{NC(PWROFF)}, I_{NO(PWROFF)}$ | $V_{NC} \text{ or } V_{NO} = 0 \text{ to } 5.5 \text{ V}$, $V_{COM} = 5.5 \text{ V to } 0$, Switch OFF, See Figure 14 | 25°C Full | 0 V | -1 -20 | 0.2 | 1 20 | μA |
| NC, NO ON leakage current | $I_{NC(ON)}, I_{NO(ON)}$ | $V_{NC} \text{ or } V_{NO} = 0 \text{ to } V_+$, $V_{COM} = \text{Open}$, Switch ON, See Figure 15 | 25°C Full | 5.5 V | -20 -100 | 2 | 20 100 | nA |
| | $I_{COM(PWROFF)}$ | $V_{COM} = 0 \text{ to } 5.5 \text{ V}$, $V_{NC} \text{ or } V_{NO} = 5.5 \text{ V to } 0$, Switch OFF, See Figure 14 | 25°C Full | 0 V | -1 -20 | 0.1 | 1 20 | μA |
| COM ON leakage current | $I_{COM(ON)}$ | $V_{COM} = 1 \text{ V}$, $V_{NC} \text{ or } V_{NO} = \text{Open}$, or $V_{COM} = 4.5 \text{ V}$, $V_{NC} \text{ or } V_{NO} = \text{Open}$, Switch ON, See Figure 15 | 25°C Full | 5.5 V | -20 -100 | 2 | 20 100 | nA |
| Digital Control Input (IN)⁽²⁾ | | | | | | | | |
| Input logic high | V_{IH} | | Full | | 2.4 | | 5.5 | V |
| Input logic low | V_{IL} | | Full | | 0 | | 0.8 | V |
| Input leakage current | I_{IH}, I_{IL} | $V_I = 5.5 \text{ V or } 0$ | 25°C Full | 5.5 V | -2 100 | | 0.2 100 | μA |

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

(2) All unused digital inputs of the device must be held at V_+ or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

ELECTRICAL CHARACTERISTICS FOR 5-V SUPPLY⁽¹⁾ (continued)
 $V_+ = 4.5\text{ V to }5.5\text{ V}$, $T_A = -40^\circ\text{C to }85^\circ\text{C}$ (unless otherwise noted)

| PARAMETER | SYMBOL | TEST CONDITIONS | T_A | V_+ | MIN | TYP | MAX | UNIT |
|---------------------------|----------------------------------|---|-------|----------------|-----|-------|-----|------|
| Dynamic | | | | | | | | |
| Turn-on time | t_{ON} | $V_{COM} = V_+$, $R_L = 50\ \Omega$, $C_L = 35\text{ pF}$, See Figure 17 | 25°C | 5 V | 2 | 3.5 | 6 | ns |
| | | | Full | 4.5 V to 5.5 V | 1 | | 8 | |
| Turn-off time | t_{OFF} | $V_{COM} = V_+$, $R_L = 50\ \Omega$, $C_L = 35\text{ pF}$, See Figure 17 | 25°C | 5 V | 3 | 8.5 | 13 | ns |
| | | | Full | 4.5 V to 5.5 V | 2 | | 15 | |
| Make-before-break time | t_{MBB} | $V_{COM} = V_+$, $R_L = 50\ \Omega$, $C_L = 35\text{ pF}$, See Figure 18 | 25°C | 5 V | 2 | 7 | 12 | ns |
| | | | Full | 5 V to 5.5 V | 2 | | 15 | |
| Charge injection | Q_C | $V_{GEN} = 0$, $R_{GEN} = 0$, $C_L = 1\text{ nF}$, See Figure 22 | 25°C | 5 V | | 36.5 | | pC |
| NC, NO OFF capacitance | $C_{NC(OFF)}$, $C_{NO(OFF)}$ | V_{NC} or $V_{NO} = V_+$ or GND, Switch OFF, See Figure 16 | 25°C | 5 V | | 18 | | pF |
| NC, NO ON capacitance | $C_{NC(ON)}$, $C_{NO(ON)}$ | V_{NC} or $V_{NO} = V_+$ or GND, Switch ON, See Figure 16 | 25°C | 5 V | | 55 | | pF |
| COM ON capacitance | $C_{COM(ON)}$ | $V_{COM} = V_+$ or GND, Switch ON, See Figure 16 | 25°C | 5 V | | 55 | | pF |
| Digital input capacitance | C_I | $V_I = V_+$ or GND, See Figure 16 | 25°C | 5 V | | 2 | | pF |
| Bandwidth | BW | $R_L = 50\ \Omega$, Switch ON, See Figure 19 | 25°C | 5 V | | 100 | | MHz |
| OFF isolation | O_{ISO} | $R_L = 50\ \Omega$, $f = 10\text{ MHz}$, See Figure 20 | 25°C | 5 V | | -64 | | dB |
| Crosstalk | X_{TALK} | $R_L = 50\ \Omega$, $f = 1\text{ MHz}$, See Figure 20 | 25°C | 5 V | | -64 | | dB |
| Total harmonic distortion | THD | $R_L = 600\ \Omega$, $C_L = 50\text{ pF}$, $f = 20\text{ Hz to }20\text{ kHz}$, See Figure 23 | 25°C | 5 V | | 0.004 | | % |
| Supply | | | | | | | | |
| Positive supply current | I_+ | $V_I = V_+$ or GND | 25°C | 5.5 V | | 10 | 50 | nA |
| | | | Full | | | | 500 | |

ELECTRICAL CHARACTERISTICS FOR 3.3-V SUPPLY⁽¹⁾
 $V_+ = 3\text{ V to }3.6\text{ V}$, $T_A = -40^\circ\text{C to }85^\circ\text{C}$ (unless otherwise noted)

| PARAMETER | SYMBOL | TEST CONDITIONS | T_A | V_+ | MIN | TYP | MAX | UNIT |
|---|--|---|--------------|-------|------|-------------|--------------|---------------|
| Analog Switch | | | | | | | | |
| Analog signal range | $V_{\text{COM}}, V_{\text{NC}}, V_{\text{NO}}$ | | | | 0 | | V_+ | V |
| Peak ON resistance | r_{peak} | $0 \leq (V_{\text{NO}} \text{ or } V_{\text{NC}}) \leq V_+$, $I_{\text{COM}} = -100\text{ mA}$, Switch ON, See Figure 13 | 25°C Full | 3 V | | 1.3 | 1.6 2 | Ω |
| ON-state resistance | r_{on} | $V_{\text{NO}} \text{ or } V_{\text{NC}} = 2\text{ V}$, $I_{\text{COM}} = -100\text{ mA}$, Switch ON, See Figure 13 | 25°C Full | 3 V | | 1.2 | 1.5 1.7 | Ω |
| ON-state resistance match between channels | Δr_{on} | $V_{\text{NO}} \text{ or } V_{\text{NC}} = 2\text{ V, }0.8\text{ V}$, $I_{\text{COM}} = -100\text{ mA}$, Switch ON, See Figure 13 | 25°C Full | 3 V | | 0.1 | 0.15 0.15 | Ω |
| ON-state resistance flatness | $r_{\text{on(flat)}}$ | $0 \leq (V_{\text{NO}} \text{ or } V_{\text{NC}}) \leq V_+$, $I_{\text{COM}} = -100\text{ mA}$, Switch ON, See Figure 13 | 25°C Full | 3 V | | 0.2 0.15 | 0.3 0.3 | Ω |
| NC, NO OFF leakage current | $I_{\text{NC(OFF)}}, I_{\text{NO(OFF)}}$ | $V_{\text{NC}} \text{ or } V_{\text{NO}} = 1\text{ V}$, $V_{\text{COM}} = 3\text{ V}$, or $V_{\text{NC}} \text{ or } V_{\text{NO}} = 3\text{ V}$, $V_{\text{COM}} = 1\text{ V}$, Switch OFF, See Figure 14 | 25°C Full | 3.6 V | -20 | 2 | 20 50 | nA |
| | $I_{\text{NC(PWROFF)}}, I_{\text{NO(PWROFF)}}$ | $V_{\text{NC}} \text{ or } V_{\text{NO}} = 0 \text{ to } 3.6\text{ V}$, $V_{\text{COM}} = 3.6\text{ V to } 0$, Switch OFF, See Figure 14 | 25°C Full | 0 V | -1 | 0.2 | 1 15 | μA |
| NC, NO ON leakage current | $I_{\text{NC(ON)}}, I_{\text{NO(ON)}}$ | $V_{\text{NC}} \text{ or } V_{\text{NO}} = 1\text{ V}$, $V_{\text{COM}} = \text{Open}$, or $V_{\text{NC}} \text{ or } V_{\text{NO}} = 3\text{ V}$, $V_{\text{COM}} = \text{Open}$, Switch ON, See Figure 15 | 25°C Full | 3.6 V | -10 | 2 | 10 20 | nA |
| COM OFF leakage current | $I_{\text{COM(PWROFF)}}$ | $V_{\text{COM}} = 0 \text{ to } 3.6\text{ V}$, $V_{\text{NC}} \text{ or } V_{\text{NO}} = 3.6\text{ V to } 0$, Switch OFF, See Figure 14 | 25°C Full | 0 V | -1 | 0.2 | 1 15 | μA |
| COM ON leakage current | $I_{\text{COM(ON)}}$ | $V_{\text{COM}} = 1\text{ V}$, $V_{\text{NC}} \text{ or } V_{\text{NO}} = \text{Open}$, or $V_{\text{COM}} = 3\text{ V}$, $V_{\text{NC}} \text{ or } V_{\text{NO}} = \text{Open}$, Switch ON, See Figure 15 | 25°C Full | 3.6 V | -10 | 2 | 10 20 | nA |
| Digital Control Input (IN)⁽²⁾ | | | | | | | | |
| Input logic high | V_{IH} | | Full | | 2 | | 5.5 | V |
| Input logic low | V_{IL} | | Full | | 0 | | 0.8 | V |
| Input leakage current | $I_{\text{IH}}, I_{\text{IL}}$ | $V_{\text{I}} = 5.5\text{ V or } 0$ | 25°C | 3.6 V | -2 | | 2 | nA |
| | | | Full | | -100 | | 100 | |

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

(2) All unused digital inputs of the device must be held at V_+ or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

ELECTRICAL CHARACTERISTICS FOR 3.3-V SUPPLY⁽¹⁾ (continued)
 $V_+ = 3\text{ V to }3.6\text{ V}$, $T_A = -40^\circ\text{C to }85^\circ\text{C}$ (unless otherwise noted)

| PARAMETER | SYMBOL | TEST CONDITIONS | T_A | V_+ | MIN | TYP | MAX | UNIT |
|---------------------------|----------------------------------|---|-------|--------------|-----|-------|-----|------|
| Dynamic | | | | | | | | |
| Turn-on time | t_{ON} | $V_{COM} = V_+$, $R_L = 50\ \Omega$, $C_L = 35\text{ pF}$, See Figure 17 | 25°C | 3.3 V | 2 | 4.5 | 13 | ns |
| | | | Full | 3 V to 3.6 V | 1 | | 15 | |
| Turn-off time | t_{OFF} | $V_{COM} = V_+$, $R_L = 50\ \Omega$, $C_L = 35\text{ pF}$, See Figure 17 | 25°C | 3.3 V | 3 | 9 | 15 | ns |
| | | | Full | 3 V to 3.6 V | 2 | | 20 | |
| Make-before-break time | t_{MBB} | $V_{COM} = V_+$, $R_L = 50\ \Omega$, $C_L = 35\text{ pF}$, See Figure 18 | 25°C | 3.3 V | 1 | 7 | 12 | ns |
| | | | Full | 3 V to 3.6 V | 1 | | 15 | |
| Charge injection | Q_C | $V_{GEN} = 0$, $R_{GEN} = 0$, $C_L = 1\text{ nF}$, See Figure 22 | 25°C | 3.3 V | | 20 | | pC |
| NC, NO OFF capacitance | $C_{NC(OFF)}$, $C_{NO(OFF)}$ | V_{NC} or $V_{NO} = V_+$ or GND, Switch OFF, See Figure 16 | 25°C | 3.3 V | | 18 | | pF |
| NC, NO ON capacitance | $C_{NC(ON)}$, $C_{NO(ON)}$ | V_{NC} or $V_{NO} = V_+$ or GND, Switch ON, See Figure 16 | 25°C | 3.3 V | | 55 | | pF |
| COM ON capacitance | $C_{COM(ON)}$ | $V_{COM} = V_+$ or GND, Switch ON, See Figure 16 | 25°C | 3.3 V | | 55 | | pF |
| Digital input capacitance | C_I | $V_I = V_+$ or GND, See Figure 16 | 25°C | 3.3 V | | 2 | | pF |
| Bandwidth | BW | $R_L = 50\ \Omega$, Switch ON, See Figure 19 | 25°C | 3.3 V | | 100 | | MHz |
| OFF isolation | O_{ISO} | $R_L = 50\ \Omega$, $f = 10\text{ MHz}$, See Figure 20 | 25°C | 3.3 V | | -64 | | dB |
| Crosstalk | X_{TALK} | $R_L = 50\ \Omega$, $f = 1\text{ MHz}$, See Figure 20 | 25°C | 3.3 V | | -64 | | dB |
| Total harmonic distortion | THD | $R_L = 600\ \Omega$, $C_L = 50\text{ pF}$, $f = 20\text{ Hz to }20\text{ kHz}$, See Figure 23 | 25°C | 3.3 V | | 0.010 | | % |
| Supply | | | | | | | | |
| Positive supply current | I_+ | $V_I = V_+$ or GND | 25°C | 3.6 V | | 10 | 30 | nA |
| | | | Full | | | | 100 | |

Electrical Characteristics for 2.5-V Supply⁽¹⁾

$V_+ = 2.3 \text{ V to } 2.7 \text{ V}$, $T_A = -40^\circ\text{C to } 85^\circ\text{C}$ (unless otherwise noted)

| PARAMETER | SYMBOL | TEST CONDITIONS | T_A | V_+ | MIN | TYP | MAX | UNIT |
|---|----------------------------------|--|--------------|-------|------|-----|-------|---------------|
| Analog Switch | | | | | | | | |
| Analog signal range | V_{COM}, V_{NC}, V_{NO} | | | | 0 | | V_+ | V |
| Peak ON resistance | r_{peak} | $0 \leq (V_{NO} \text{ or } V_{NC}) \leq V_+$, $I_{COM} = -8 \text{ mA}$, Switch ON, See Figure 13 | 25°C Full | 2.3 V | 1.8 | 2.5 | 2.7 | Ω |
| ON-state resistance | r_{on} | $V_{NO} \text{ or } V_{NC} = 1.8 \text{ V}$, $I_{COM} = -8 \text{ mA}$, Switch ON, See Figure 13 | 25°C Full | 2.3 V | 1.5 | 2 | 2.4 | Ω |
| ON-state resistance match between channels | Δr_{on} | $V_{NO} \text{ or } V_{NC} = 1.8 \text{ V}$, $I_{COM} = -8 \text{ mA}$, Switch ON, See Figure 13 | 25°C Full | 2.3 V | 0.15 | 0.2 | 0.2 | Ω |
| ON-state resistance flatness | $r_{on(flat)}$ | $0 \leq (V_{NO} \text{ or } V_{NC}) \leq V_+$, $I_{COM} = -8 \text{ mA}$, Switch ON, See Figure 13 | 25°C Full | 2.3 V | 2.6 | 0.6 | 1 | Ω |
| NC, NO OFF leakage current | $I_{NC(OFF)}, I_{NO(OFF)}$ | $V_{NC} \text{ or } V_{NO} = 0.5 \text{ V}$, $V_{COM} = 2.2 \text{ V}$, or $V_{NC} \text{ or } V_{NO} = 2.2 \text{ V}$, $V_{COM} = 0.5 \text{ V}$, Switch OFF, See Figure 14 | 25°C Full | 2.3 V | -20 | 2 | 20 | nA |
| | $I_{NC(PWROFF)}, I_{NO(PWROFF)}$ | $V_{NC} \text{ or } V_{NO} = 0 \text{ to } 2.7 \text{ V}$, $V_{COM} = 2.7 \text{ V to } 0$, Switch OFF, See Figure 14 | 25°C Full | 0 V | -1 | 0.1 | 1 | μA |
| NC, NO ON leakage current | $I_{NC(ON)}, I_{NO(ON)}$ | $V_{NC} \text{ or } V_{NO} = 0.5 \text{ V}$, $V_{COM} = \text{Open}$, or $V_{NC} \text{ or } V_{NO} = 2.2 \text{ V}$, $V_{COM} = \text{Open}$, Switch ON, See Figure 15 | 25°C Full | 2.7 V | -10 | 2 | 10 | nA |
| COM OFF leakage current | $I_{COM(PWROFF)}$ | $V_{COM} = 0 \text{ to } 2.7 \text{ V}$, $V_{NC} \text{ or } V_{NO} = 2.7 \text{ V to } 0$, Switch OFF, See Figure 14 | 25°C Full | 0 V | -1 | 0.1 | 1 | μA |
| COM ON leakage current | $I_{COM(ON)}$ | $V_{COM} = 0.5 \text{ V}$, $V_{NC} \text{ or } V_{NO} = \text{Open}$, or $V_{COM} = 2.2 \text{ V}$, $V_{NC} \text{ or } V_{NO} = \text{Open}$, Switch ON, See Figure 15 | 25°C Full | 2.7 V | -10 | 2 | 10 | nA |
| Digital Control Input (IN)⁽²⁾ | | | | | | | | |
| Input logic high | V_{IH} | | Full | | 1.8 | | 5.5 | V |
| Input logic low | V_{IL} | | Full | | 0 | | 0.6 | V |
| Input leakage current | I_{IH}, I_{IL} | $V_I = 5.5 \text{ V or } 0$ | 25°C | 2.7 V | -2 | | 2 | nA |
| | | | Full | | -20 | | 20 | |

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

(2) All unused digital inputs of the device must be held at V_+ or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics for 2.5-V Supply⁽¹⁾ (continued)
 $V_+ = 2.3 \text{ V to } 2.7 \text{ V}$, $T_A = -40^\circ\text{C to } 85^\circ\text{C}$ (unless otherwise noted)

| PARAMETER | SYMBOL | TEST CONDITIONS | T_A | V_+ | MIN | TYP | MAX | UNIT |
|---------------------------|----------------------------------|--|-------|----------------|-----|------|-----|------|
| Dynamic | | | | | | | | |
| Turn-on time | t_{ON} | $V_{COM} = V_+$, $R_L = 50 \Omega$, $C_L = 35 \text{ pF}$, See Figure 17 | 25°C | 2.5 V | 2 | 6.5 | 15 | ns |
| | | | Full | 2.3 V to 2.7 V | 1 | | 17 | |
| Turn-off time | t_{OFF} | $V_{COM} = V_+$, $R_L = 50 \Omega$, $C_L = 35 \text{ pF}$, See Figure 17 | 25°C | 2.5 V | 3 | 11 | 18 | ns |
| | | | Full | 2.3 V to 2.7 V | 2 | | 20 | |
| Make-before-break time | t_{MBB} | $V_{COM} = V_+$, $R_L = 50 \Omega$, $C_L = 35 \text{ pF}$, See Figure 18 | 25°C | 2.5 V | 1 | 8 | 12 | ns |
| | | | Full | 2.3 V to 2.7 V | 1 | | 15 | |
| Charge injection | Q_C | $V_{GEN} = 0$, $R_{GEN} = 0$, $C_L = 1 \text{ nF}$, See Figure 22 | 25°C | 2.5 V | | 12 | | pC |
| NC, NO OFF capacitance | $C_{NC(OFF)}$, $C_{NO(OFF)}$ | V_{NC} or $V_{NO} = V_+$ or GND, Switch OFF, See Figure 16 | 25°C | 2.5 V | | 18 | | pF |
| NC, NO ON capacitance | $C_{NC(ON)}$, $C_{NO(ON)}$ | V_{NC} or $V_{NO} = V_+$ or GND, Switch ON, See Figure 16 | 25°C | 2.5 V | | 55 | | pF |
| COM ON capacitance | $C_{COM(ON)}$ | $V_{COM} = V_+$ or GND, Switch ON, See Figure 16 | 25°C | 2.5 V | | 55 | | pF |
| Digital input capacitance | C_I | $V_I = V_+$ or GND, See Figure 16 | 25°C | 2.5 V | | 2 | | pF |
| Bandwidth | BW | $R_L = 50 \Omega$, Switch ON, See Figure 19 | 25°C | 2.5 V | | 100 | | MHz |
| OFF isolation | O_{ISO} | $R_L = 50 \Omega$, $f = 10 \text{ MHz}$, See Figure 20 | 25°C | 2.5 V | | -64 | | dB |
| Crosstalk | X_{TALK} | $R_L = 50 \Omega$, $f = 1 \text{ MHz}$, See Figure 20 | 25°C | 2.5 V | | -64 | | dB |
| Total harmonic distortion | THD | $R_L = 600 \Omega$, $C_L = 50 \text{ pF}$, $f = 20 \text{ Hz to } 20 \text{ kHz}$, See Figure 23 | 25°C | 2.5 V | | 0.02 | | % |
| Supply | | | | | | | | |
| Positive supply current | I_+ | $V_I = V_+$ or GND | 25°C | 2.7 V | | 10 | 30 | nA |
| | | | Full | | | | 50 | |

ELECTRICAL CHARACTERISTICS FOR 1.8-V SUPPLY⁽¹⁾
 $V_+ = 1.65 \text{ V to } 1.95 \text{ V}$, $T_A = -40^\circ\text{C to } 85^\circ\text{C}$ (unless otherwise noted)

| PARAMETER | SYMBOL | TEST CONDITIONS | | T _A | V ₊ | MIN | TYP | MAX | UNIT |
|--|--|--|------------------------------|----------------|----------------|------|-----|----------------|------|
| Analog Switch | | | | | | | | | |
| Analog signal range | V _{COM} , V _{NC} , V _{NO} | | | | | 0 | | V ₊ | V |
| Peak ON resistance | r _{peak} | 0 ≤ (V _{NO} or V _{NC}) ≤ V ₊ , I _{COM} = −2 mA, | Switch ON, See Figure 13 | 25°C | 1.65 V | 5 | | 15 | Ω |
| | | | | Full | | | | | |
| ON-state resistance | r _{on} | V _{NO} or V _{NC} = 1.5 V, I _{COM} = −2 mA, | Switch ON, See Figure 13 | 25°C | 1.65 V | 2 | | 2.5 | Ω |
| | | | | Full | | 3.5 | | | |
| ON-state resistance match between channels | Δr _{on} | V _{NO} or V _{NC} = 1.5 V, I _{COM} = −2 mA, | Switch ON, See Figure 13 | 25°C | 1.65 V | 0.15 | | 0.4 | Ω |
| | | | | Full | | 0.4 | | | |
| ON-state resistance flatness | r _{on(flat)} | 0 ≤ (V _{NO} or V _{NC}) ≤ V ₊ , I _{COM} = −2 mA, | Switch ON, See Figure 13 | 25°C | 1.65 V | 5 | | | Ω |
| | | V _{NO} or V _{NC} = 0.6 V, 1.5 V, I _{COM} = −2 mA, | Switch ON, See Figure 13 | 25°C | | 4.5 | | | |
| | | | | Full | | | | | |
| NC, NO OFF leakage current | I _{NC(OFF)} , I _{NO(OFF)} | V _{NC} or V _{NO} = 0.3 V, V _{COM} = 1.65 V, or V _{NC} or V _{NO} = 1.65 V, V _{COM} = 0.3 V, | Switch OFF, See Figure 14 | 25°C | 1.95 V | −5 | 2 | 5 | nA |
| | | | | Full | | −20 | | 20 | |
| | I _{NC(PWROFF)} , I _{NO(PWROFF)} | V _{NC} or V _{NO} = 0 to 1.95 V, V _{COM} = 1.95 V to 0, | Switch OFF, See Figure 14 | 25°C | 0 V | −1 | 0.1 | 1 | μA |
| | | | | Full | | −5 | | 5 | |
| NC, NO ON leakage current | I _{NC(ON)} , I _{NO(ON)} | V _{NC} or V _{NO} = 0.3 V, V _{COM} = Open, or V _{NC} or V _{NO} = 1.65 V, V _{COM} = Open, | Switch ON, See Figure 15 | 25°C | 1.95 V | −5 | 2 | 5 | nA |
| | | | | Full | | −20 | | 20 | |
| COM OFF leakage current | I _{COM(PWROFF)} | V _{COM} = 0 to 1.95 V, V _{NC} or V _{NO} = 1.95 V to 0, | Switch OFF, See Figure 14 | 25°C | 0 V | −1 | 0.1 | 1 | μA |
| | | | | Full | | −5 | | 5 | |
| COM ON leakage current | I _{COM(ON)} | V _{COM} = 0.3 V, V _{NC} or V _{NO} = Open, or V _{COM} = 1.65 V, V _{NC} or V _{NO} = Open, | Switch ON, See Figure 15 | 25°C | 1.95 V | −5 | 2 | 5 | nA |
| | | | | Full | | −20 | | 20 | |
| Digital Control Input (IN) ⁽²⁾ | | | | | | | | | |
| Input logic high | V _{IH} | | | Full | | 1.5 | | 5.5 | V |
| Input logic low | V _{IL} | | | Full | | 0 | | 0.6 | V |
| Input leakage current | I _{IH} , I _{IL} | V _I = 5.5 V or 0 | | 25°C | 1.95 V | −2 | | 2 | nA |
| | | | | Full | | −20 | | 20 | |

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

(2) All unused digital inputs of the device must be held at V_+ or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

ELECTRICAL CHARACTERISTICS FOR 1.8-V SUPPLY⁽¹⁾ (continued)

$V_+ = 1.65\text{ V to }1.95\text{ V}$, $T_A = -40^\circ\text{C to }85^\circ\text{C}$ (unless otherwise noted)

| PARAMETER | SYMBOL | TEST CONDITIONS | T_A | V_+ | MIN | TYP | MAX | UNIT |
|---------------------------|----------------------------------|---|-------|----------------|-----|------|-----|------|
| Dynamic | | | | | | | | |
| Turn-on time | t_{ON} | $V_{COM} = V_+$, $R_L = 50\ \Omega$, $C_L = 35\text{ pF}$, See Figure 17 | 25°C | 1.8 V | 6 | 13 | 24 | ns |
| | | | Full | 2.3 V to 2.7 V | 5 | | 27 | |
| Turn-off time | t_{OFF} | $V_{COM} = V_+$, $R_L = 50\ \Omega$, $C_L = 35\text{ pF}$, See Figure 17 | 25°C | 1.8 V | 6 | 15 | 27 | ns |
| | | | Full | 2.3 V to 2.7 V | 5 | | 30 | |
| Make-before-break time | t_{MBB} | $V_{COM} = V_+$, $R_L = 50\ \Omega$, $C_L = 35\text{ pF}$, See Figure 18 | 25°C | 1.8 V | 2 | 7 | 12 | ns |
| | | | Full | 2.3 V to 2.7 V | 2 | | 15 | |
| Charge injection | Q_C | $V_{GEN} = 0$, $R_{GEN} = 0$, $C_L = 1\text{ nF}$, See Figure 22 | 25°C | 1.8 V | | 5.5 | | pC |
| NC, NO OFF capacitance | $C_{NC(OFF)}$, $C_{NO(OFF)}$ | V_{NC} or $V_{NO} = V_+$ or GND, Switch OFF, | 25°C | 1.8 V | | 18 | | pF |
| NC, NO ON capacitance | $C_{NC(ON)}$, $C_{NO(ON)}$ | V_{NC} or $V_{NO} = V_+$ or GND, Switch ON, | 25°C | 1.8 V | | 55 | | pF |
| COM ON capacitance | $C_{COM(ON)}$ | $V_{COM} = V_+$ or GND, Switch ON, | 25°C | 1.8 V | | 55 | | pF |
| Digital input capacitance | C_I | $V_I = V_+$ or GND, | 25°C | 1.8 V | | 2 | | pF |
| Bandwidth | BW | $R_L = 50\ \Omega$, Switch ON, | 25°C | 1.8 V | | 105 | | MHz |
| OFF isolation | O_{ISO} | $R_L = 50\ \Omega$, $f = 10\text{ MHz}$, | 25°C | 1.8 V | | -64 | | dB |
| Crosstalk | X_{TALK} | $R_L = 50\ \Omega$, $f = 1\text{ MHz}$, | 25°C | 1.8 V | | -64 | | dB |
| Total harmonic distortion | THD | $R_L = 600\ \Omega$, $C_L = 50\text{ pF}$, $f = 20\text{ Hz to }20\text{ kHz}$, See Figure 23 | 25°C | 1.8 V | | 0.06 | | % |
| Supply | | | | | | | | |
| Positive supply current | I_+ | $V_I = V_+$ or GND | 25°C | 1.95 V | | 5 | 15 | nA |
| | | | Full | | | | 50 | |

TYPICAL PERFORMANCE

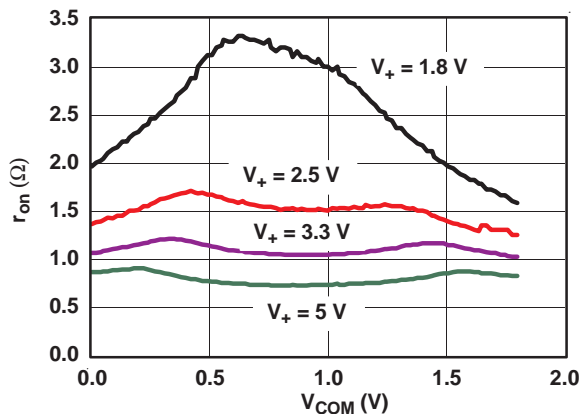


Figure 1. r_{on} vs V_{COM}

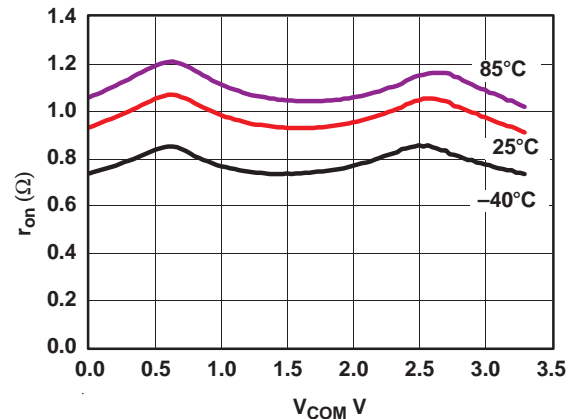
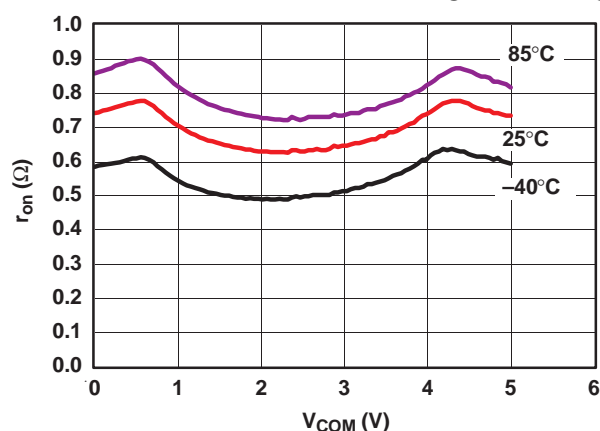
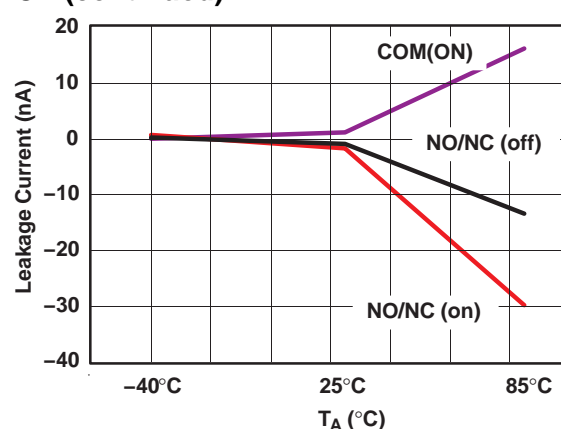
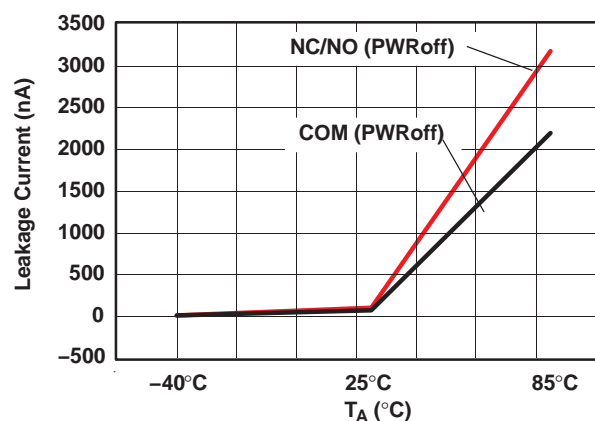
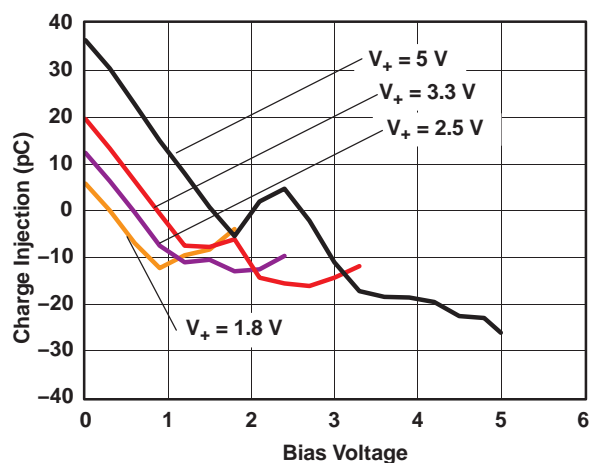
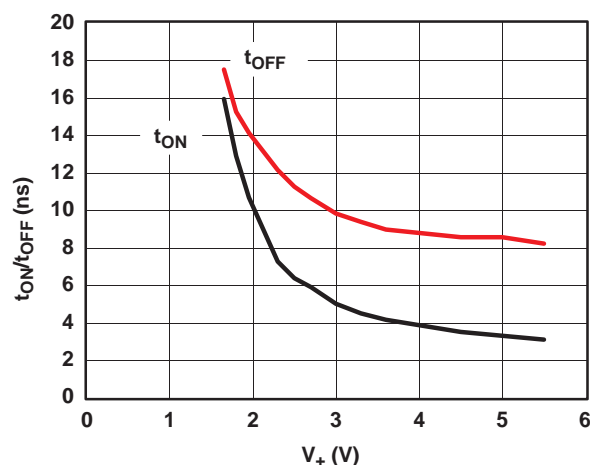
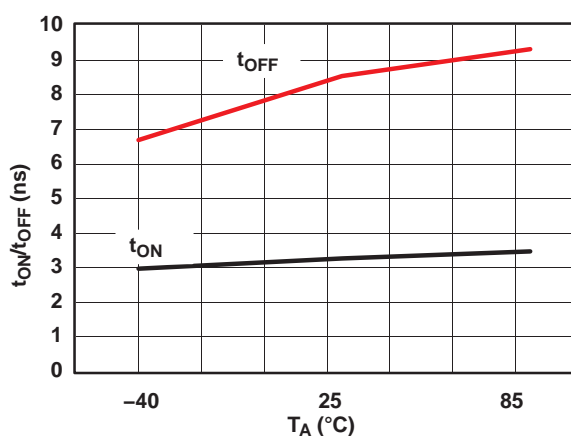


Figure 2. r_{on} vs V_{COM} ($V_+ = 3.3\text{ V}$)

TYPICAL PERFORMANCE (continued)Figure 3. r_{on} vs V_{COM} ($V_+ = 5$ V)Figure 4. Leakage Current vs Temperature ($V_+ = 5.5$ V)Figure 5. Leakage Current vs Temperature ($V_+ = 5$ V)Figure 6. Charge Injection (Q_C) vs V_{COM} Figure 7. t_{ON} and t_{OFF} vs Supply VoltageFigure 8. t_{ON} and t_{OFF} vs Temperature ($V_+ = 5$ V)

TYPICAL PERFORMANCE (continued)

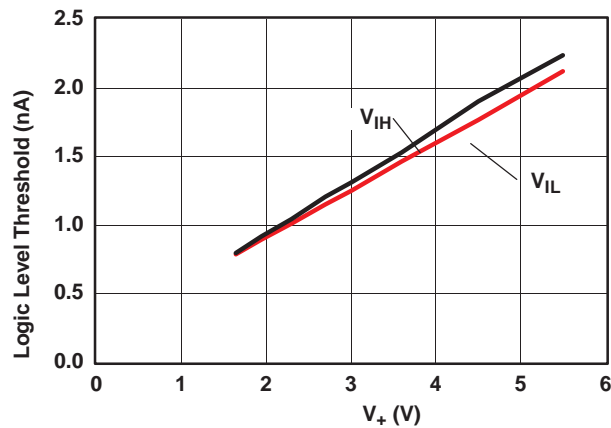


Figure 9. Logic-Level Threshold vs V_+

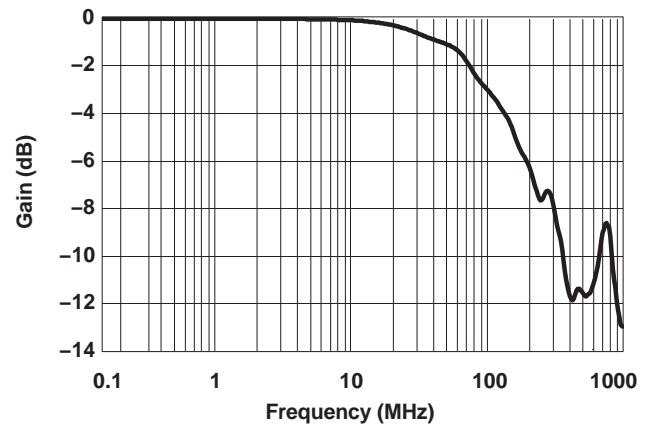


Figure 10. Bandwidth (Gain vs Frequency) ($V_+ = 5$ V)

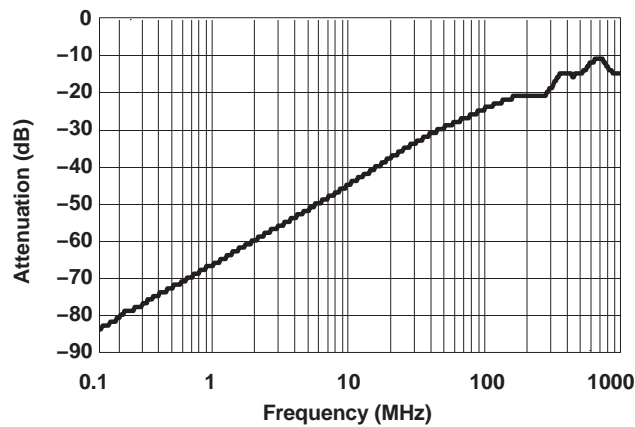


Figure 11. OFF Isolation vs Crosstalk ($V_+ = 5$ V)

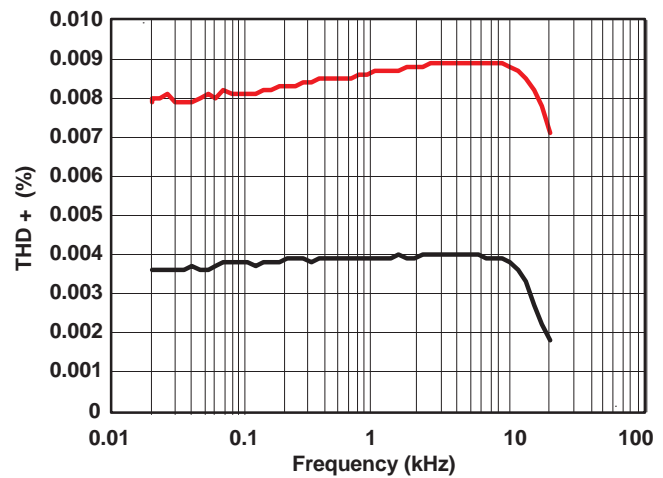


Figure 12. Total Harmonic Distortion vs Frequency

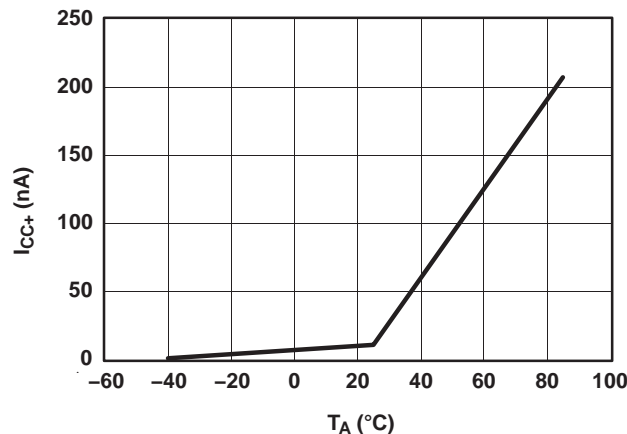


Figure 13. Power-Supply Current vs Temperature
($V_+ = 5$ V)

Table 3. PIN DESCRIPTION

| PIN NUMBER | NAME | DESCRIPTION |
|------------|----------------|--------------------------------------|
| 1 | NO | Normally open |
| 2 | GND | Digital ground |
| 3 | NC | Normally closed |
| 4 | COM | Common |
| 5 | V ₊ | Power supply |
| 6 | IN | Digital control to connect COM to NO |

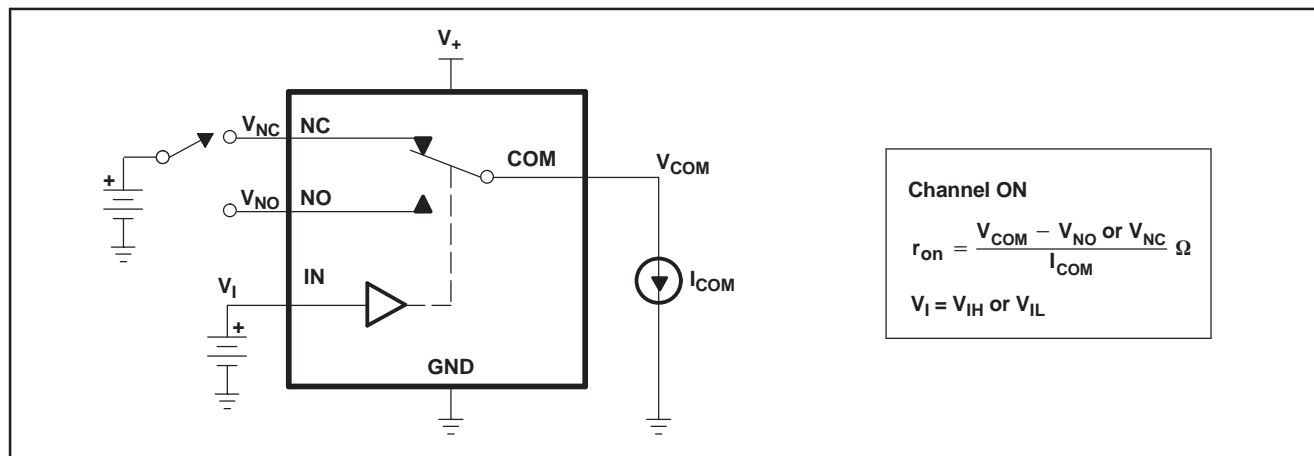
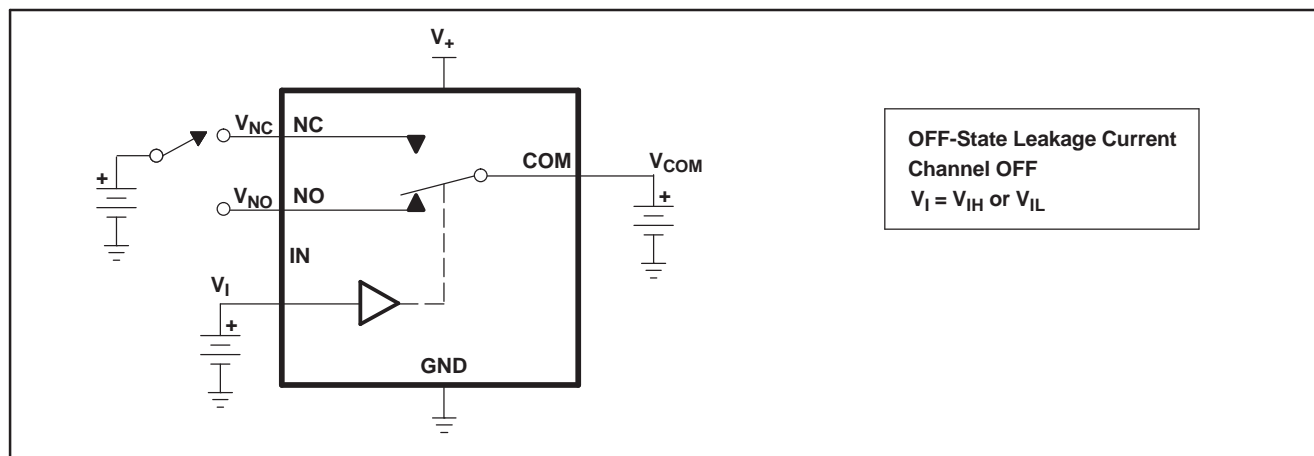
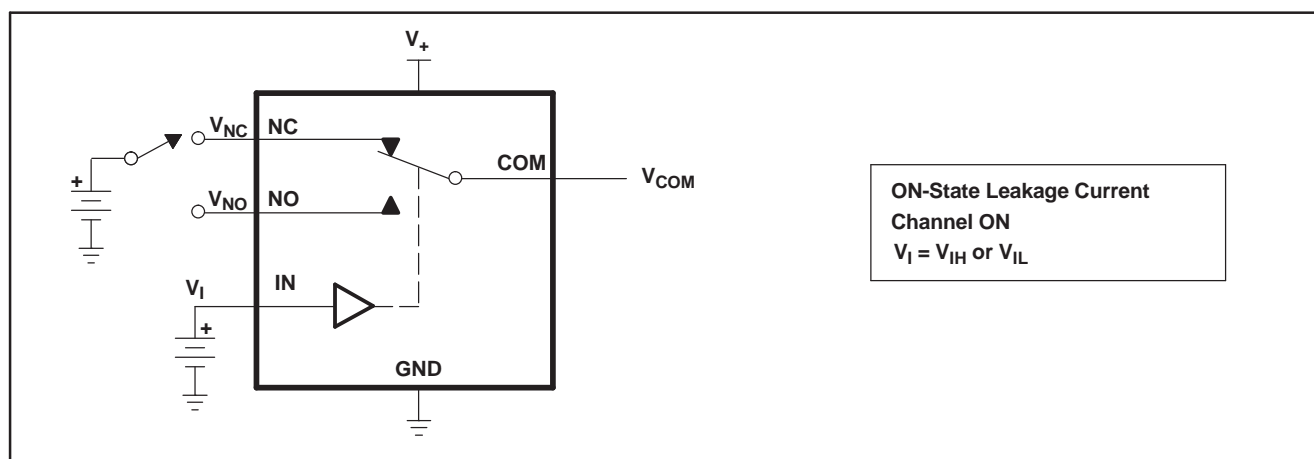
Table 4. PARAMETER DESCRIPTION

| SYMBOL | DESCRIPTION |
|-----------------------------------|--|
| V _{COM} | Voltage at COM |
| V _{NC} | Voltage at NC |
| V _{NO} | Voltage at NO |
| r _{on} | Resistance between COM and NO ports when the channel is ON |
| r _{peak} | Peak on-state resistance over a specified voltage range |
| Δr _{on} | Difference of r _{on} between channels in a specific device |
| r _{on(flat)} | Difference between the maximum and minimum value of r _{on} in a channel over the specified range of conditions |
| I _{NC(OFF)} | Leakage current measured at the NC port, with the corresponding channel (NC to COM) in the OFF state under worst-case input and output conditions |
| I _{NC(PWROFF)} | Leakage current measured at the NC port during the power-off condition, V ₊ = 0 |
| I _{NO(OFF)} | Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the OFF state |
| I _{NO(PWROFF)} | Leakage current measured at the NO port during the power-off condition, V ₊ = 0 |
| I _{NC(ON)} | Leakage current measured at the NC port, with the corresponding channel (NC to COM) in the ON state and the output (COM) open |
| I _{NO(ON)} | Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the ON state and the output (COM) open |
| I _{NO(OFF)} | Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the OFF state and the output (COM) open |
| I _{NO(ON)} | Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the ON state and the output (COM) open |
| I _{COM(OFF)} | Leakage current measured at the COM port, with the corresponding channel (COM to NO) in the OFF state |
| I _{COM(PWROFF)} | Leakage current measured at the COM port during the power-off condition, V ₊ = 0 |
| I _{COM(ON)} | Leakage current measured at the COM port, with the corresponding channel (COM to NO) in the ON state and the output (NO) open |
| V _{IH} | Minimum input voltage for logic high for the control input (IN) |
| V _{IL} | Maximum input voltage for logic low for the control input (IN) |
| V _I | Voltage at the control input (IN) |
| I _{IH} , I _{IL} | Leakage current measured at the control input (IN) |
| t _{ON} | Turn-on time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM or NO) signal when the switch is turning ON. |
| t _{OFF} | Turn-off time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM or NO) signal when the switch is turning OFF. |
| t _{MBB} | Make-before-break time. This parameter is measured under the specified range of conditions and by the propagation delay between the output of two adjacent analog channels (NC and NO) when the control signal changes state. |
| Q _C | Charge injection is a measurement of unwanted signal coupling from the control (IN) input to the analog (NO or COM) output. This is measured in coulomb (C) and measured by the total charge induced due to switching of the control input. Charge injection, Q _C = C _L × ΔV _{COM} . C _L is the load capacitance and ΔV _{COM} is the change in analog output voltage. |
| C _{NC(OFF)} | Capacitance at the NC port when the corresponding channel (NC to COM) is OFF |
| C _{NO(OFF)} | Capacitance at the NO port when the corresponding channel (NO to COM) is OFF |
| C _{NC(ON)} | Capacitance at the NC port when the corresponding channel (NC to COM) is ON |

Table 4. PARAMETER DESCRIPTION (continued)

| SYMBOL | DESCRIPTION |
|---------------|--|
| $C_{NO(ON)}$ | Capacitance at the NO port when the corresponding channel (NO to COM) is ON |
| $C_{COM(ON)}$ | Capacitance at the COM port when the corresponding channel (COM to NO) is ON |
| C_I | Capacitance of IN |
| O_{ISO} | OFF isolation of the switch is a measurement of OFF-state switch impedance. This is measured in dB in a specific frequency, with the corresponding channel (NO to COM) in the OFF state. |
| X_{TALK} | Crosstalk is a measurement of unwanted signal coupling from an ON channel to an adjacent ON channel (NC1 to NC2). This is measured in a specific frequency and in dB. |
| BW | Bandwidth of the switch. This is the frequency in which the gain of an ON channel is -3 dB below the DC gain. |
| THD | Total harmonic distortion is defined as the ratio of the root mean square (RMS) value of the second, third, and higher harmonics to the magnitude of fundamental harmonic. |
| I_+ | Static power-supply current with the control (IN) pin at V_+ or GND |

PARAMETER MEASUREMENT INFORMATION

Figure 14. ON-State Resistance (r_{on})Figure 15. OFF-State Leakage Current ($I_{NC(OFF)}$, $I_{NO(OFF)}$, $I_{COM(OFF)}$, $I_{NC(PWROFF)}$, $I_{NO(PWROFF)}$, $I_{COM(PWROFF)}$)Figure 16. ON-State Leakage Current ($I_{COM(ON)}$, $I_{NC(ON)}$, $I_{NO(ON)}$)

PARAMETER MEASUREMENT INFORMATION (continued)

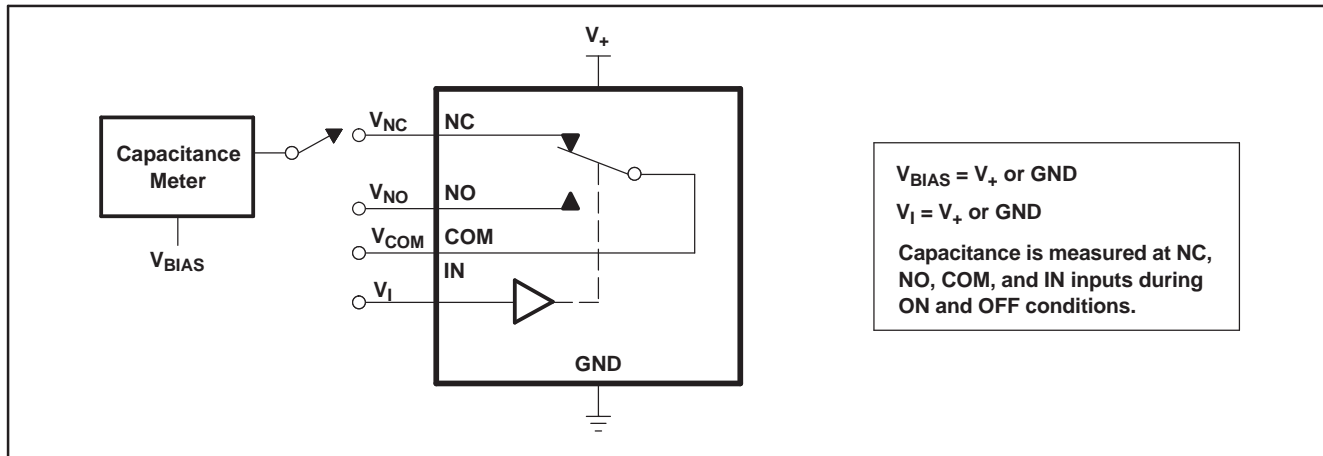


Figure 17. Capacitance (C_I , $C_{COM(ON)}$, $C_{NC(OFF)}$, $C_{NO(OFF)}$, $C_{NC(ON)}$, $C_{NO(ON)}$)

- All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r < 5 \text{ ns}$, $t_f < 5 \text{ ns}$.
- C_L includes probe and jig capacitance.

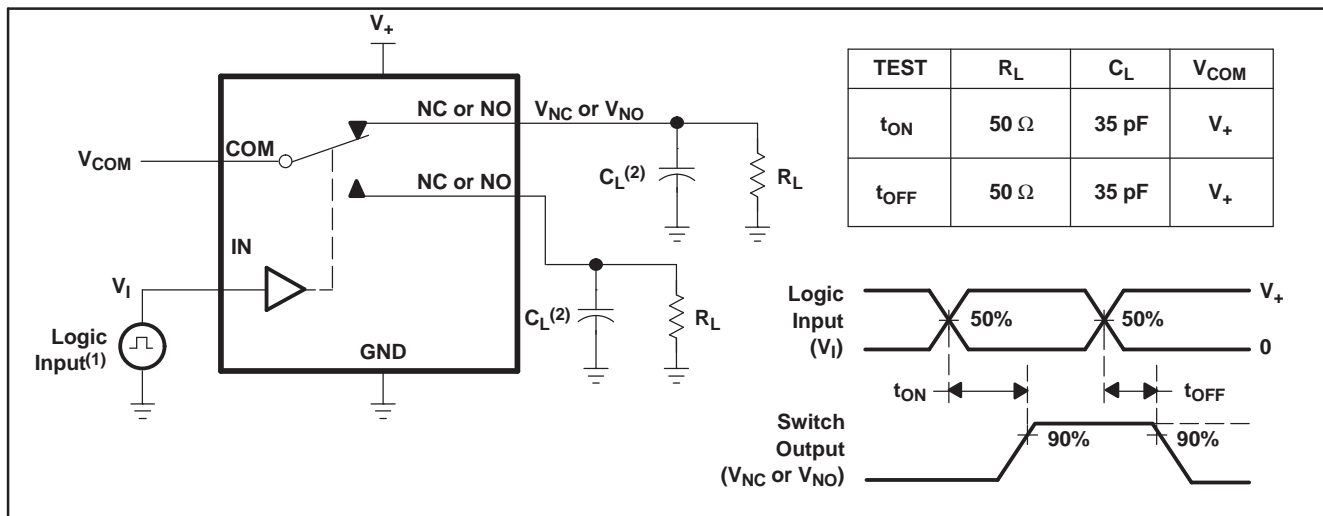
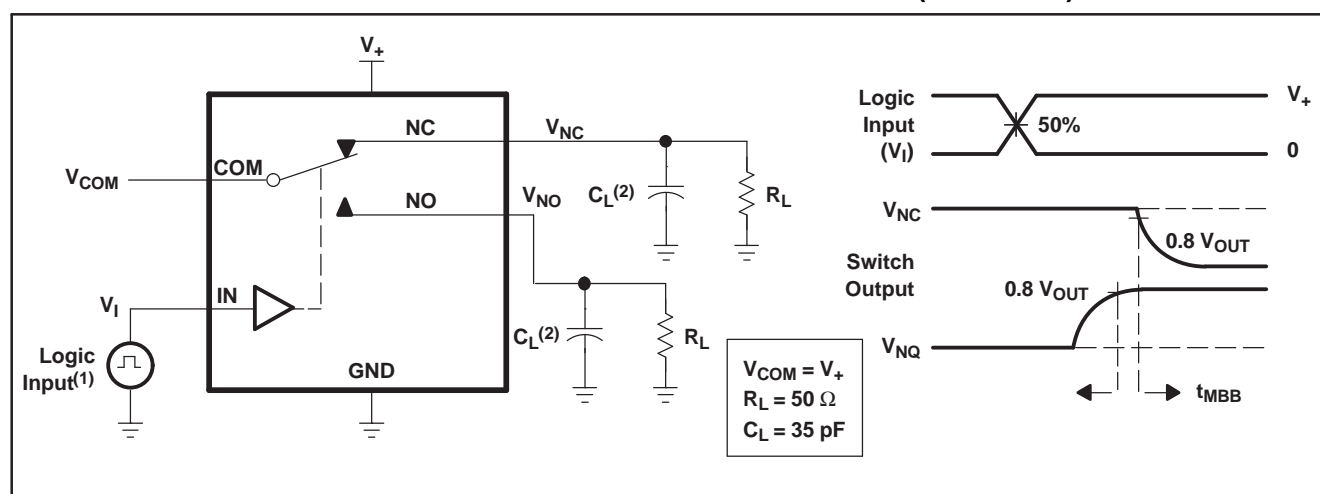
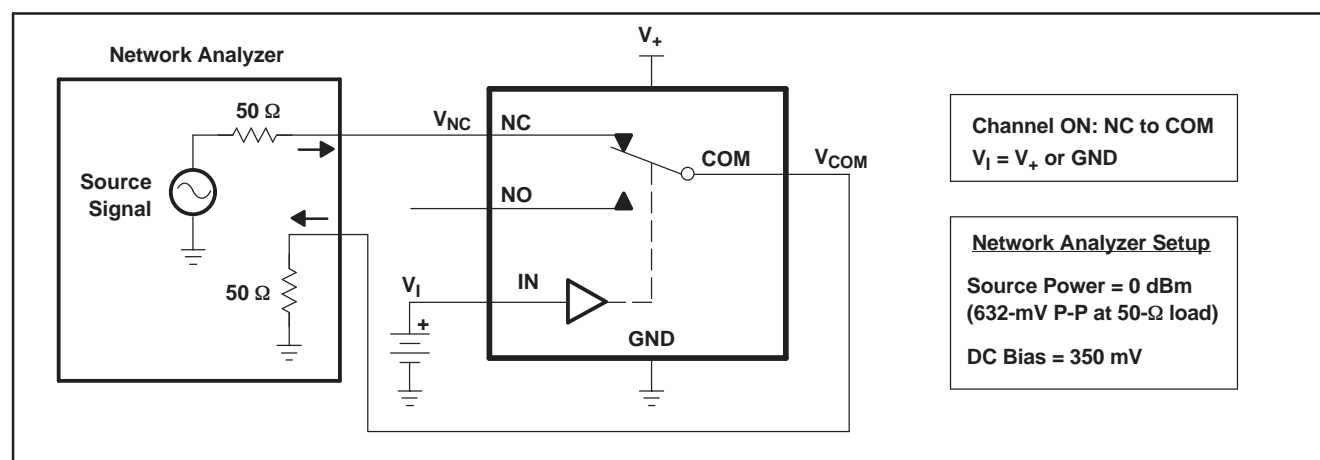
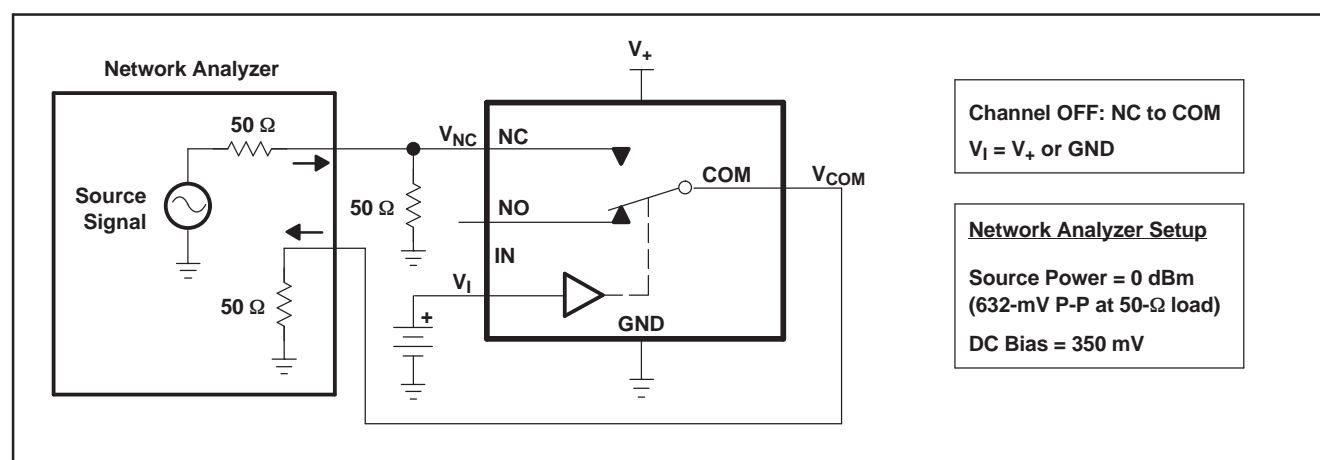


Figure 18. Turn-On (t_{ON}) and Turn-Off Time (t_{OFF})

- All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r < 5 \text{ ns}$, $t_f < 5 \text{ ns}$.
- C_L includes probe and jig capacitance.

PARAMETER MEASUREMENT INFORMATION (continued)**Figure 19. Make-Before-Break Time (t_{MBB})****Figure 20. Bandwidth (BW)****Figure 21. OFF Isolation (OISO)**

PARAMETER MEASUREMENT INFORMATION (continued)

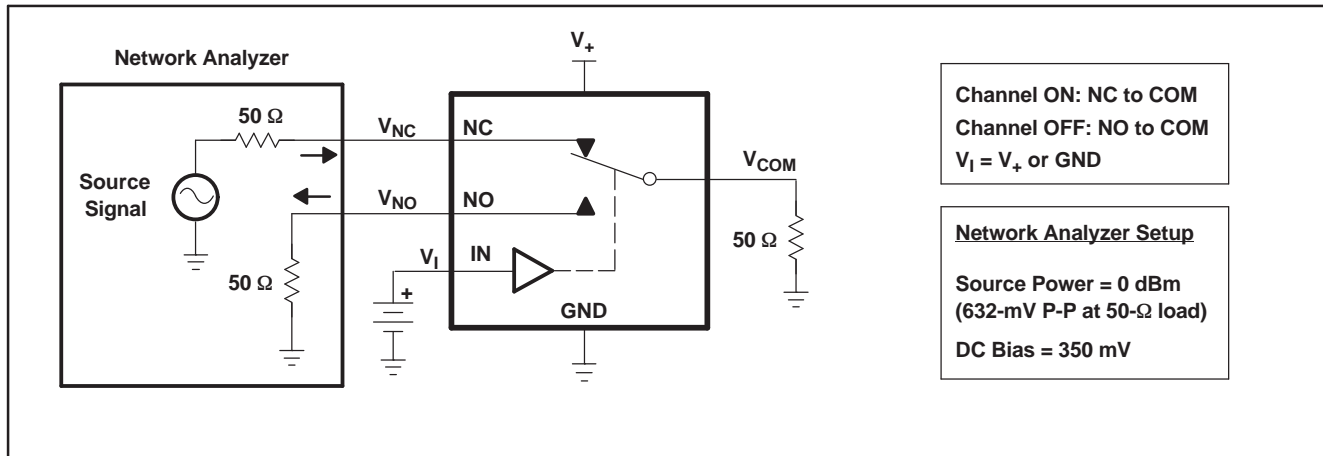


Figure 22. Crosstalk (X_{TALK})

- (1) All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $t_r < 5$ ns, $t_f < 5$ ns.
- A. C_L includes probe and jig capacitance.

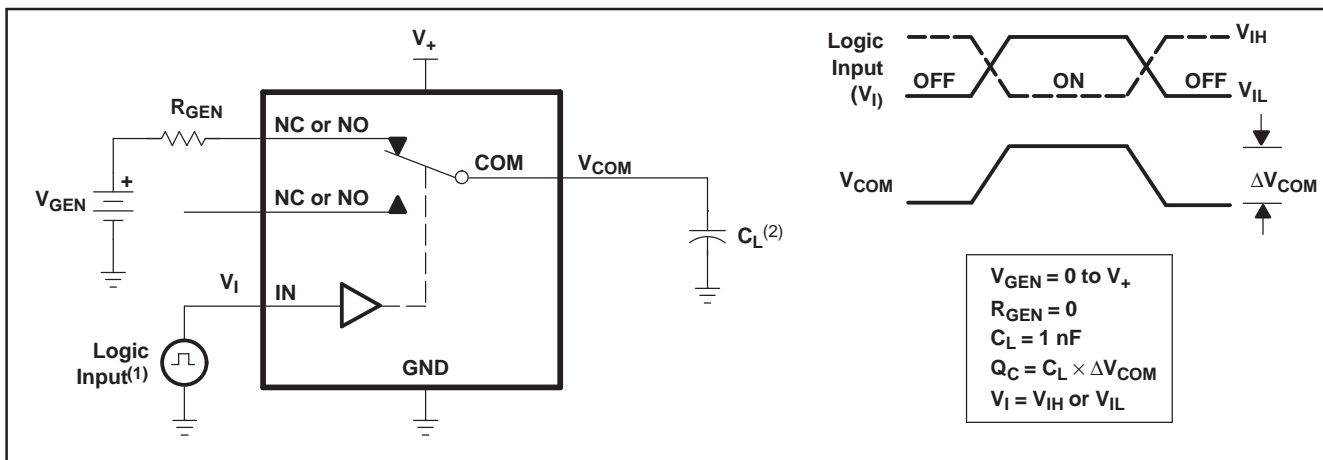
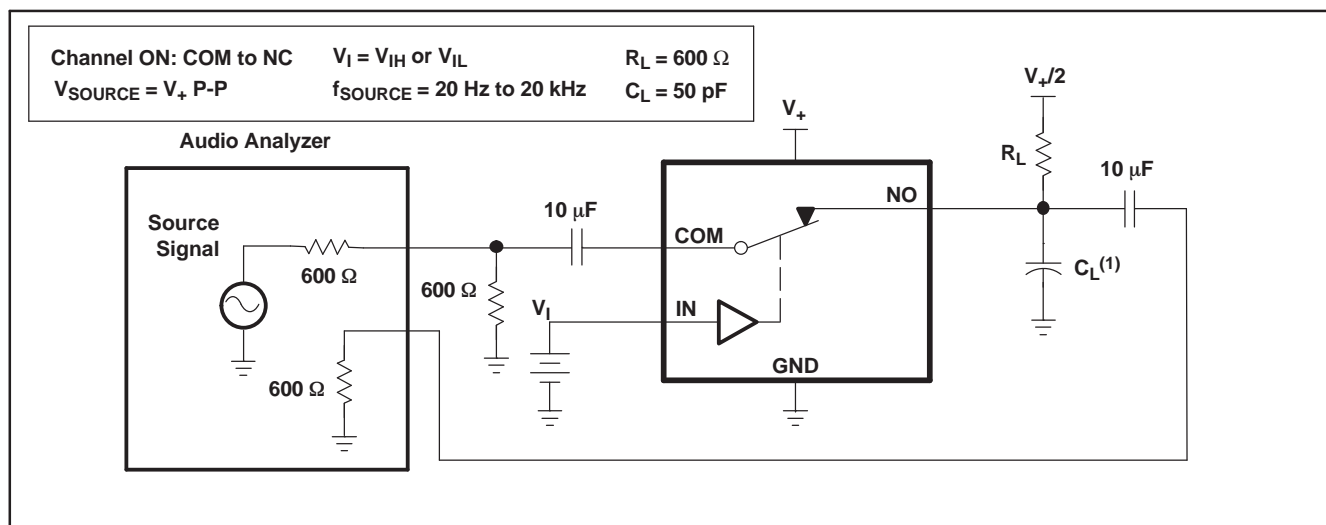


Figure 23. Charge Injection (Q_C)

PARAMETER MEASUREMENT INFORMATION (continued)**Figure 24. Total Harmonic Distortion (THD)**

REVISION HISTORY

Changes from Revision B (June 2011) to Revision C

Page

- Corrected the top side marking for all orderable parts. [1](#)

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Top-Side Markings (4) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|------------------|----------------------|--------------|--------------------------|-------------------------|
| TS5A3160DBVR | ACTIVE | SOT-23 | DBV | 6 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | JAKR | Samples |
| TS5A3160DBVRE4 | ACTIVE | SOT-23 | DBV | 6 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | JAKR | Samples |
| TS5A3160DBVRG4 | ACTIVE | SOT-23 | DBV | 6 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | JAKR | Samples |
| TS5A3160DBVT | ACTIVE | SOT-23 | DBV | 6 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | JAKR | Samples |
| TS5A3160DBVTE4 | ACTIVE | SOT-23 | DBV | 6 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | JAKR | Samples |
| TS5A3160DBVTG4 | ACTIVE | SOT-23 | DBV | 6 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | JAKR | Samples |
| TS5A3160DCKJ | ACTIVE | SC70 | DCK | 6 | 10000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | (JKK ~ JKR) | Samples |
| TS5A3160DCKR | ACTIVE | SC70 | DCK | 6 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | (JKK ~ JKR) | Samples |
| TS5A3160DCKRE4 | ACTIVE | SC70 | DCK | 6 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | (JKK ~ JKR) | Samples |
| TS5A3160DCKRG4 | ACTIVE | SC70 | DCK | 6 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | (JKK ~ JKR) | Samples |
| TS5A3160DCKT | ACTIVE | SC70 | DCK | 6 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | (JKK ~ JKR) | Samples |
| TS5A3160DCKTE4 | ACTIVE | SC70 | DCK | 6 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | (JKK ~ JKR) | Samples |
| TS5A3160DCKTG4 | ACTIVE | SC70 | DCK | 6 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | (JKK ~ JKR) | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


| | |
|----|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

TAPE AND REEL INFORMATION

*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|-------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TS5A3160DBVR | SOT-23 | DBV | 6 | 3000 | 180.0 | 8.4 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| TS5A3160DBVT | SOT-23 | DBV | 6 | 250 | 180.0 | 8.4 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| TS5A3160DCKJ | SC70 | DCK | 6 | 10000 | 330.0 | 8.4 | 2.3 | 2.55 | 1.2 | 4.0 | 8.0 | Q3 |
| TS5A3160DCKR | SC70 | DCK | 6 | 3000 | 180.0 | 9.2 | 2.3 | 2.55 | 1.2 | 4.0 | 8.0 | Q3 |
| TS5A3160DCKT | SC70 | DCK | 6 | 250 | 180.0 | 9.2 | 2.3 | 2.55 | 1.2 | 4.0 | 8.0 | Q3 |

TAPE AND REEL BOX DIMENSIONS



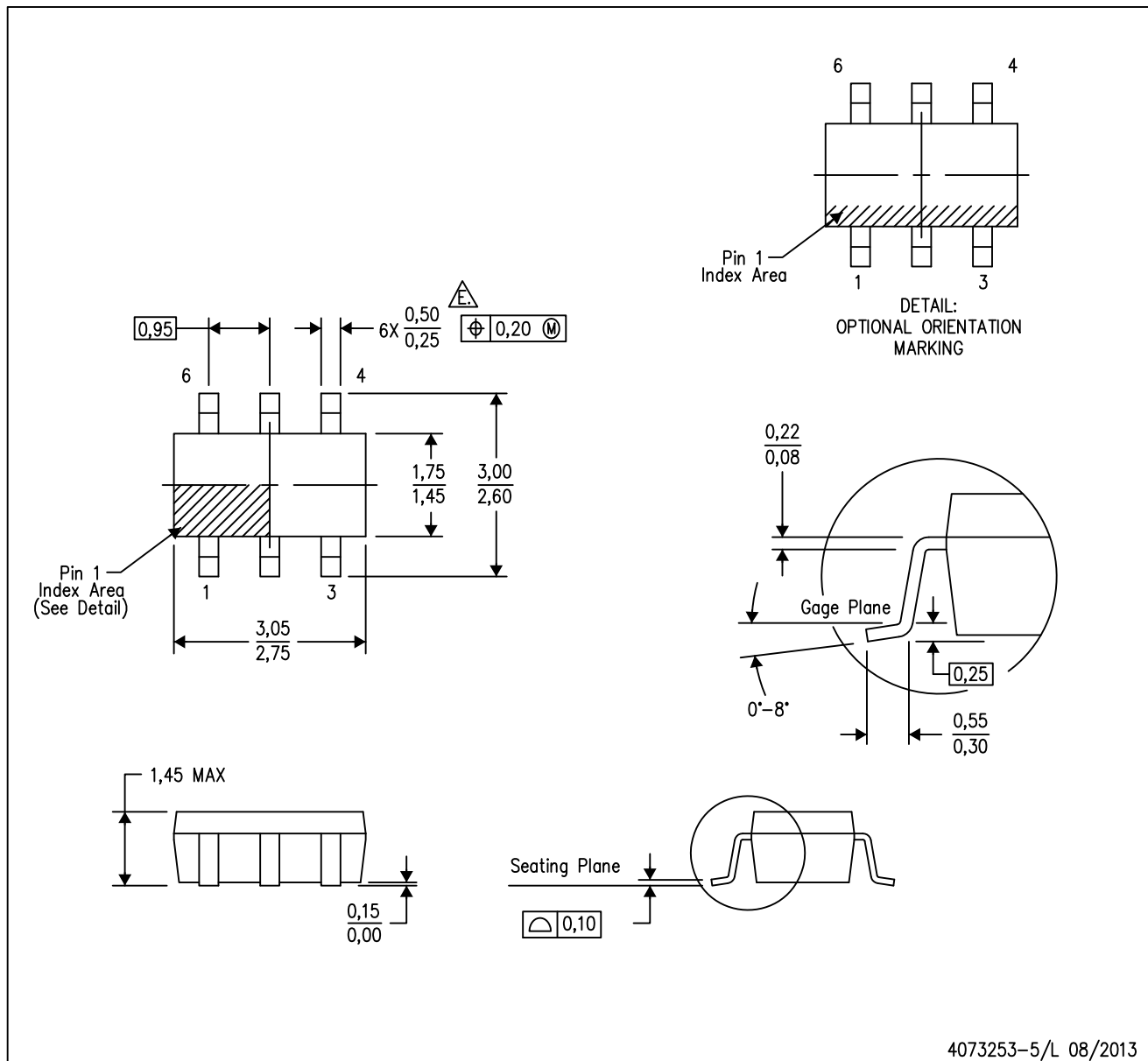
*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|-------|-------------|------------|-------------|
| TS5A3160DBVR | SOT-23 | DBV | 6 | 3000 | 202.0 | 201.0 | 28.0 |
| TS5A3160DBVT | SOT-23 | DBV | 6 | 250 | 202.0 | 201.0 | 28.0 |
| TS5A3160DCKJ | SC70 | DCK | 6 | 10000 | 182.0 | 182.0 | 20.0 |
| TS5A3160DCKR | SC70 | DCK | 6 | 3000 | 205.0 | 200.0 | 33.0 |
| TS5A3160DCKT | SC70 | DCK | 6 | 250 | 205.0 | 200.0 | 33.0 |

MECHANICAL DATA

DBV (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
 - E. Falls within JEDEC MO-178 Variation AB, except minimum lead width.

DBV (R-PDSO-G6)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

DCK (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



4093553-4/G 01/2007

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - Falls within JEDEC MO-203 variation AB.

DCK (R-PDSO-G6)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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